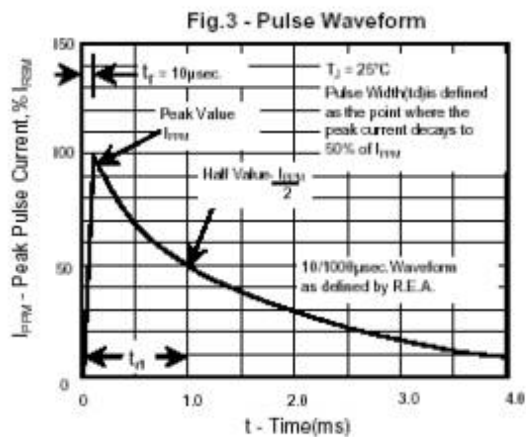
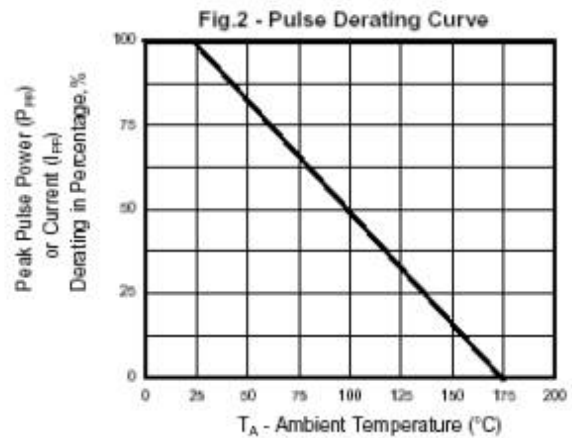
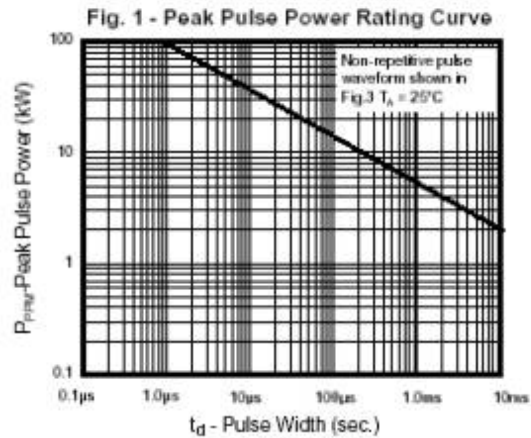
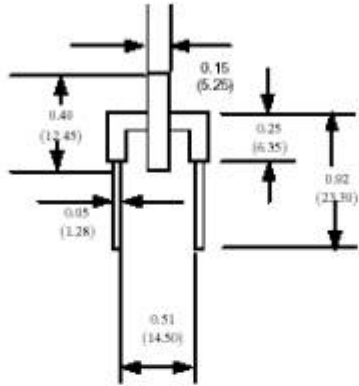


TRANSIEN K SERIES TVS **SPECIFICATION**

TransinK SERIES - TransinK - 25M **(SILICON-AVALANCHE HIGH SURGE DIODES)**



TransinK SERIES - TransinK - 25M**(SILICON-AVALANCHE HIGH SURGE DIODES)**

Dimensions in inches and (millimeters)

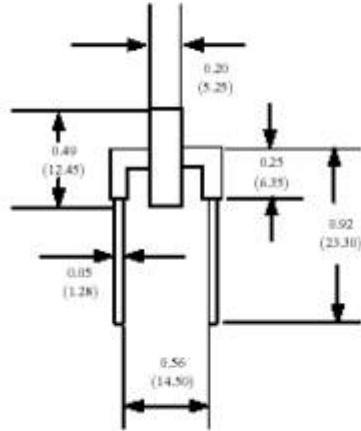
FEATURES

- Glass passivated chip junction
- 1000A surge capability at 8 x 20μsec waveform (per IEC-61000-4-5)
- Excellent clamping capability
- Repetition rate • duty cycle • 0.05 •
- Low incremental surge resistance
- Fast response time • typically less than 1.0μs from 0 Volts to BV
- Operation temperature • -40 • +125 •
- Epoxy encapsulated has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA**Terminal** • Ag Plated Axial leads, solderable per MIL-STD-750, Method 2026**Mounting Position** • Any**Weight** • 0.088±0.01 ounces • 2.497±0.283g •

RATING	SYMBOL	VALUE	UNITS
Breakdown voltage @ IT=1.0 mA	VBr	25±5%	Volt
Clamping Voltage @ 400A / 10x1000 • sec waveform	VC	34.5 max	Volt
Reverse Leakage @ 21.25V	IR	20 • (max)	A

TransinK SERIES - TransinK - 50M
(SILICON-AVALANCHE HIGH SURGE DIODES)



Dimensions in inches and (millimeters)

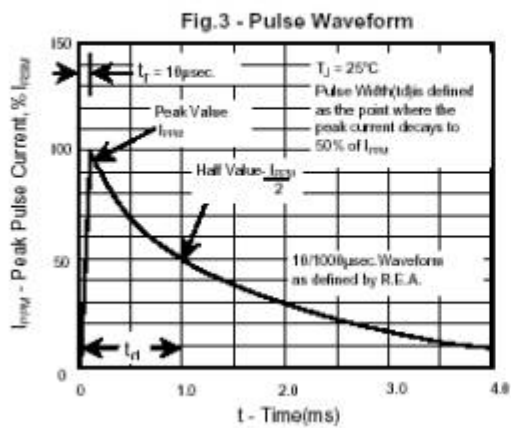
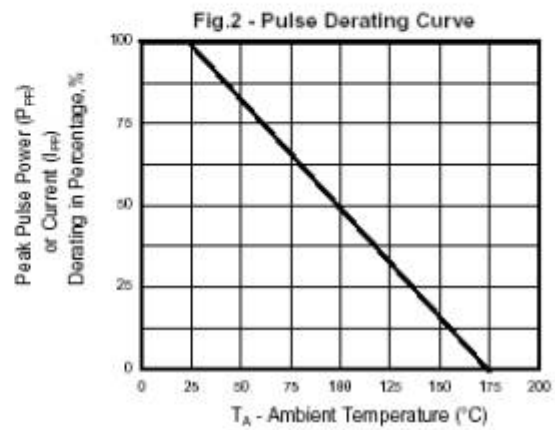
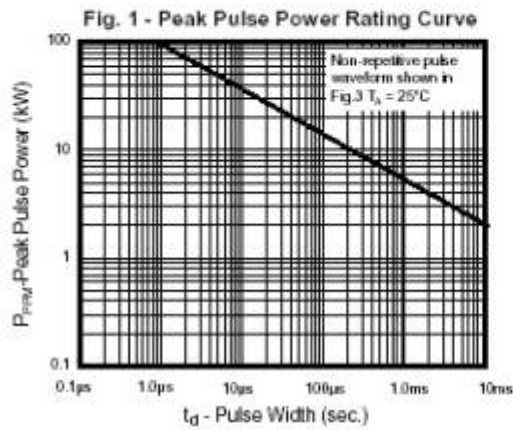
FEATURES

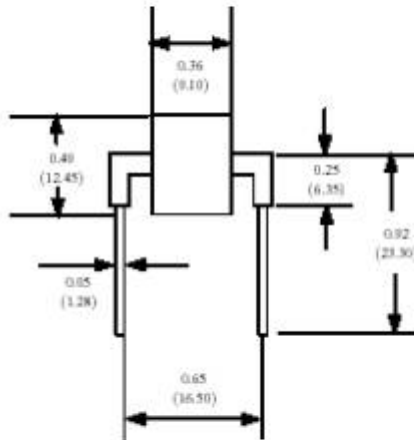
- Glass passivated chip junction
- 1000A surge capability at 8 x 20μsec waveform
 - per IEC-61000-4-5 •
- Excellent clamping capability
- Repetition rate • duty cycle • • 0.05 • •
- Low incremental surge resistance
- Fast response time • typically less than 1.0μs from 0 Volts to BV
- Operation temperature • -40 • +125 • •
- Epoxy encapsulated has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA**Terminal** • Ag Plated Axial leads, solderable per MIL-STD-750, Method 2026**Mounting Position** • Any**Weight** • 0.088±0.01 ounces • 2.497±0.283g • •

RATING	SYMBOL	VALUE	UNITS
Breakdown voltage @ IT=1.0 mA	VBr	50±5%	Volt
Clamping Voltage @400A /10x1000 • sec waveform	VC	68.85 max	Volt
Reverse Leakage @ 45.9V	IR	20 • tmax	A

TransinK SERIES - TransinK - 50M (SILICON-AVALANCHE HIGH SURGE DIODES)



TransinK SERIES - TransinK-100M**(SILICON-AVALANCHE HIGH SURGE DIODES)**

Dimensions in inches and (millimeters)

FEATURES

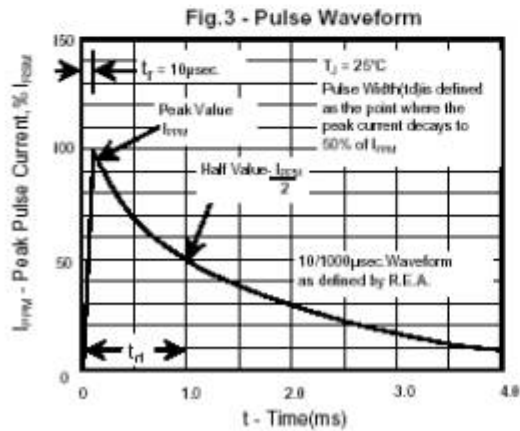
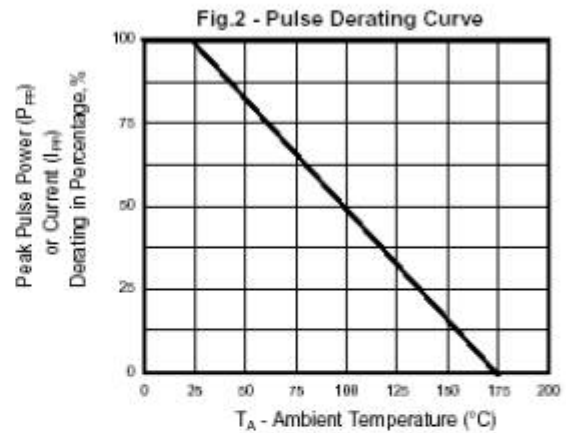
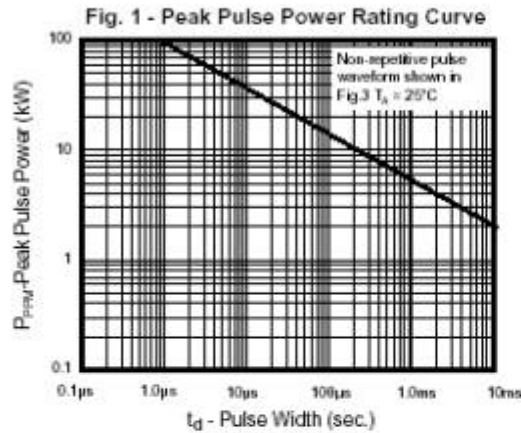
- Glass passivated chip junction
- 1000A surge capability at 8 x 20μsec waveform
 - per IEC-61000-4-5 •
- Excellent clamping capability
- Repetition rate • duty cycle • 0.05 •
- Low incremental surge resistance
- Fast response time • typically less than 1.0μs from 0 Volts to BV
- Operation temperature • -40 • +125 •
- Epoxy encapsulated has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA**Terminal** • Ag Plated Axial leads, solderable per MIL-STD-750, Method 2026**Mounting Position** • Any**Weight** • 0.188±0.019 ounces • 5.340±0.534g •

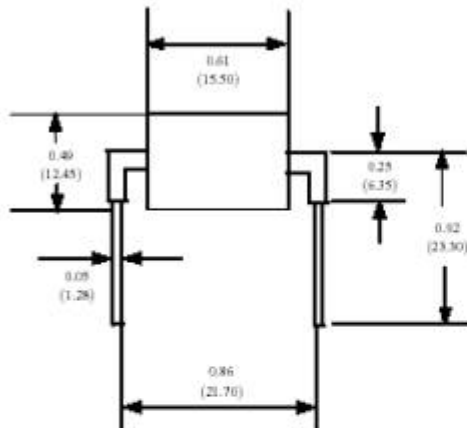
RATING	SYMBOL	VALUE	UNITS
Breakdown voltage @ IT=1.0 mA	VBr	100±5%	Volt
Clamping Voltage @ 400A / 10x1000 • sec waveform	VC	135 max	Volt
Reverse Leakage @ 91.8V	IR	20 • tmax)	A

TransinK SERIES - TransinK - 100M

(SILICON-AVALANCHE HIGH SURGE DIODES)



TransinK SERIES - TransinK-200M
(SILICON-AVALANCHE HIGH SURGE DIODES)



Dimensions in inches and (millimeters)

FEATURES

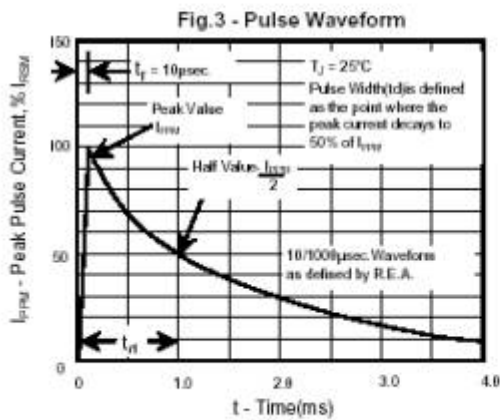
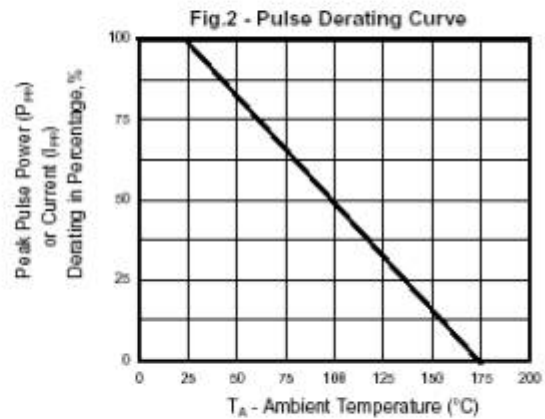
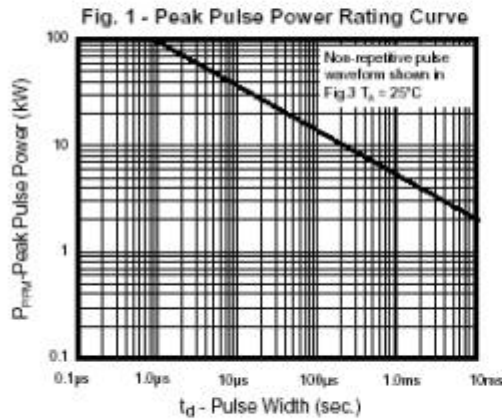
- Glass passivated chip junction
- 1000A surge capability at 8 x 20μsec waveform
 - per IEC-61000-4-5 •
- Excellent clamping capability
- Repetition rate • duty cycle • 0.05 •
- Low incremental surge resistance
- Fast response time • typically less than 1.0μs from 0 Volts to BV
- Operation temperature • -40 • +125 •
- Epoxy encapsulated has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA**Terminal** • Ag Plated Axial leads, solderable per MIL-STD-750, Method 2026**Mounting Position** • Any**Weight** • 0.328±0.033 ounces • 9.300±0.930g •

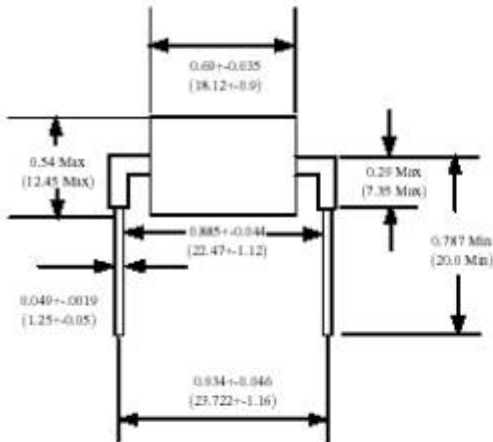
RATING	SYMBOL	VALUE	UNITS
Breakdown voltage @ IT=1.0 mA	VBr	200±5%	Volt
Clamping Voltage @400A /10x1000• sec waveform	VC	266 max	Volt
Reverse Leakage @ 181.8V	IR	20• (max)	A

TransinK SERIES - TransinK - 200M

(SILICON-AVALANCHE HIGH SURGE DIODES)



TransinK SERIES - TransinK-225M
(SILICON-AVALANCHE HIGH SURGE DIODES)



Dimensions in inches and (millimeters)

FEATURES

- Glass passivated chip junction
- 1000A surge capability at 8 x 20 μ sec waveform
 - per IEC-61000-4-5 •
- Excellent clamping capability
- Repetition rate • duty cycle • 0.05 •
- Low incremental surge resistance
- Fast response time • typically less than 1.0 μ s from 0 Volts to BV
- Operation temperature • 40 • 125 •
- Epoxy encapsulated has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA**Terminal** • Ag Plated Axial leads, solderable per MIL-STD-750, Method 2026**Mounting Position** • Any**Weight** • 0.408 $\pm$ 0.040 ounces • 11.300 $\pm$ 1.130g •

RATING	SYMBOL	VALUE	UNITS
Breakdown voltage @ IT=1.0 mA	VBr	200 $\pm$ 5%	Volt
Clamping Voltage @400A /10x1000• sec waveform	VC	266 max	Volt
Reverse Leakage @ 181.8V	IR	20• (max)	A

TransinK SERIES - TransinK - 225M

(SILICON-AVALANCHE HIGH SURGE DIODES)

